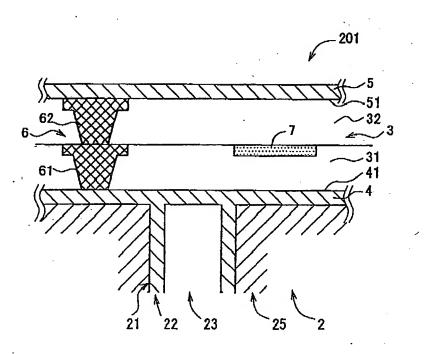
Hajime SAIKI, et al. Q80149 WIRING SUBSTRATE Filing Date: February 27, 2004 Mark Boland 202-663-7949 1 of 10

Fig. 1



Hajime SAIKI, et al. Q80149 WIRING SUBSTRATE Filing Date: February 27, 2004 Mark Boland 202-663-7949 2 of 10

" Fig. 2

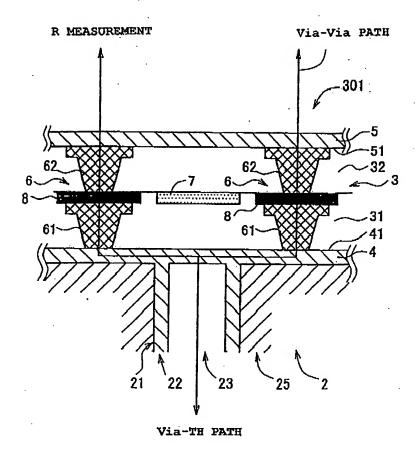
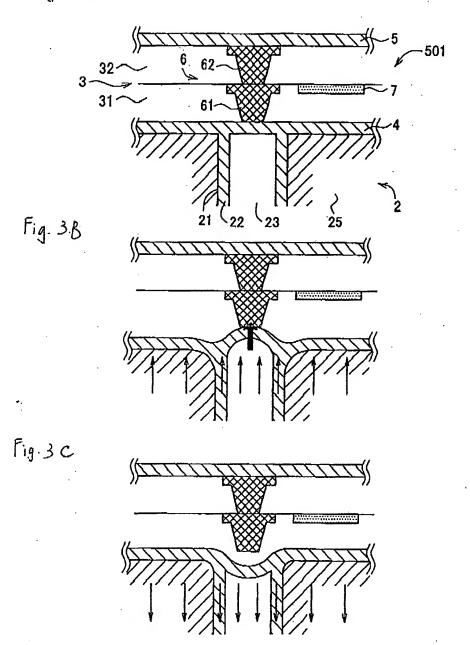
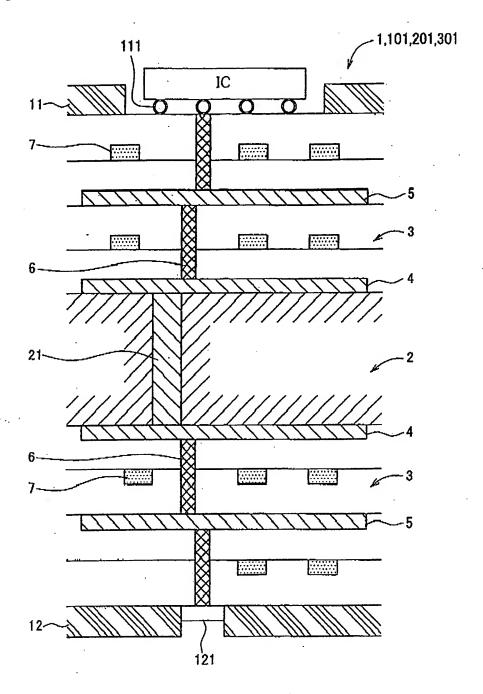


Fig. 3A



Hajime SAIKI, et al. Q80149 WIRING SUBSTRATE Filing Date: February 27, 2004 Mark Boland 202-663-7949 4 of 10

Fig. 4



Hajime SAIKI, et al. Q80149 WIRING SUBSTRATE Filing Date: February 27, 2004 Mark Boland 202-663-7949 5 of 10

 J. 5			EXAMPLE :	1
		. /	COMPARIS	ON 1
		実施例1	北較例	
	一部サイクル無し	0/30	5/30	
	2009イクル後	0/30	20/30	
	- ③500サイクル後	0/30	28/30	
	AFTER 100 CY	CLES		

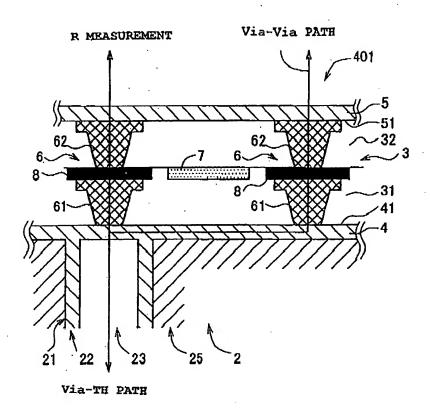


Fig 7

EXAMPLE 2

COMPARISON 2

Via-Via PATH <1% 5%

Via-TH PATH <1% 20%

Hajime SAIKI, et al. Q80149 WIRING SUBSTRATE Filing Date: February 27, 2004 Mark Boland 202-663-7949 7 of 10

Fig. 8A

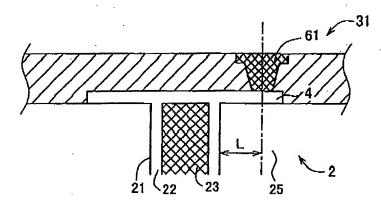
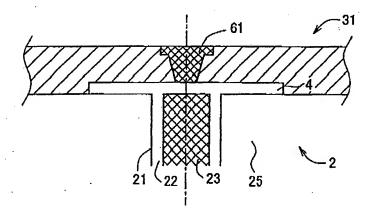
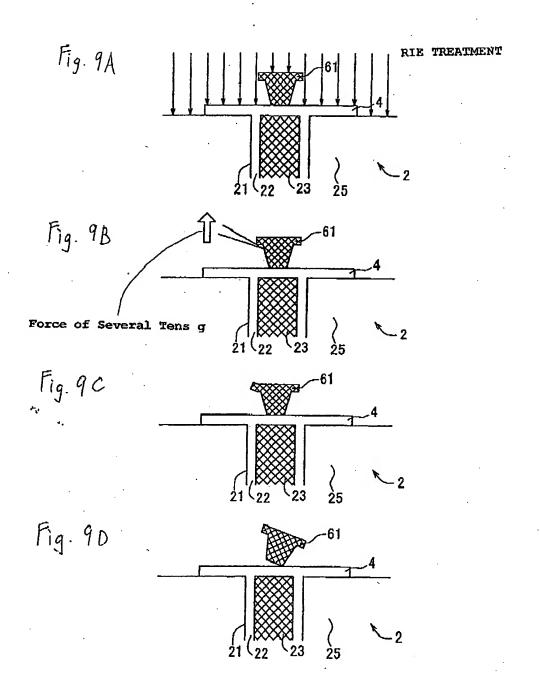


Fig. 8B





Hajime SAIKI, et al. Q80149 WIRING SUBSTRATE Filing Date: February 27, 2004 Mark Boland 202-663-7949 9 of 10

Fig. 10

VIA PEELING PERCENTAGES					
EXAMPLE 3					
COMPARISON 3					
	実施例3	比較例3			
ビア剥離率	0/30	18/25			

Hajime SAIKI, et al. Q80149 WIRING SUBSTRATE Filing Date: February 27, 2004 Mark Boland 202-663-7949 10 of 10

